

[INPUT/OUTPUT STRUCTURE AND INTEGRATED CIRCUIT USING THE SAME]

Abstract

An input/output structure for a die to support an Accelerated Graphic Port (AGP) standard and a Peripheral Component Interconnection Express (PCIE) standard is provided. The I/O structure is suitable for the die pad. It comprises: a PCIE input/output pad for supporting PCIE standard; an AGP input/output pad for supporting AGP standard; a die pad coupled to an external circuit; a first conducting distributed wire coupled to the PCIE input/output pad and the die pad; and a second conducting distributed wire coupled to the AGP input/output pad and the die pad; wherein only one of the PCIE input/output pad and the AGP input/output pad is enabled at the same time.